IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. The IGBT is well suited for half bridge resonant applications. Incorporated into the device is a soft and fast co–packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Low Gate Charge
- Soft, Fast Free Wheeling Diode
- These are Pb-Free Devices

Typical Applications

- Inductive Heating
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V_{CES}	600	V
Collector current @ Tc = 25°C @ Tc = 100°C	I _C	60 30	A
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	150	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	I _F	60 30	А
Diode pulsed current, T_{pulse} limited by T_{Jmax}	I _{FM}	150	Α
Gate-emitter voltage	V_{GE}	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	250 50	W
Operating junction temperature range	TJ	–55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

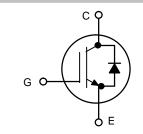
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

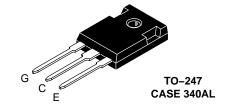


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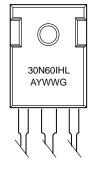
www.onsemi.com

30 A, 600 V V_{CEsat} = 1.8 V E_{off} = 0.28 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB30N60IHLWG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

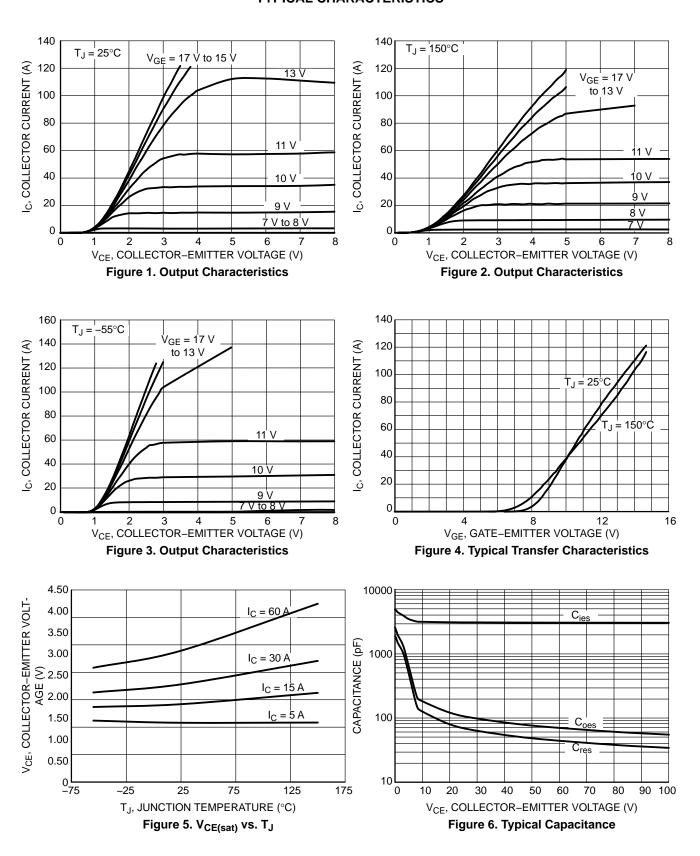
Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.87	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.46	°C/W
Thermal resistance junction-to-ambient	$R_{ heta JA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC				•		•
Collector–emitter breakdown voltage, gate–emitter short–circuited	$V_{GE} = 0 \text{ V, I}_{C} = 500 \mu\text{A}$	V _{(BR)CES}	600	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 30 A V _{GE} = 15 V, I _C = 30 A, T _J = 150°C	V _{CEsat}		1.8 2.2	2.3	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 250 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector–emitter cut–off current, gate– emitter short–circuited	V _{GE} = 0 V, V _{CE} = 600 V V _{GE} = 0 V, V _{CE} = 600 V, T _J = 150°C	I _{CES}	_	_ _	0.2 2	mA
Gate leakage current, collector–emitter short–circuited	V _{GE} = 20 V , V _{CE} = 0 V	I _{GES}	_	_	100	nA
DYNAMIC CHARACTERISTIC		•		•		•
Input capacitance		C _{ies}	-	3100	-	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	120	-	1
Reverse transfer capacitance	1	C _{res}	-	80	-	1
Gate charge total		Q_g		130		nC
Gate to emitter charge	$V_{CE} = 480 \text{ V}, I_{C} = 30 \text{ A}, V_{GE} = 15 \text{ V}$	Q _{ge}		27		
Gate to collector charge	1	Q _{gc}		65		
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-on delay time		t _{d(on)}		70		ns
Rise time	T _J = 25°C	t _r		30		
Turn-off delay time	$V_{CC} = 400 \text{ V}, I_{C} = 30 \text{ A}$ $R_{g} = 10 \Omega$	t _{d(off)}		140		
Fall time	$V_{GE} = 0 \text{ V}/15\text{V}$	t _f		80		
Turn-off switching loss		E _{off}		0.28		mJ
Turn-on delay time		t _{d(on)}		70		ns
Rise time	T _J = 150°C	t _r		32		
Turn-off delay time	$V_{CC} = 400 \text{ V, } I_{C} = 30 \text{ A}$ $R_{g} = 10 \Omega$ $V_{GE} = 0 \text{ V/ } 15 \text{V}$	t _{d(off)}		150		1
Fall time		t _f		100		1
Turn-off switching loss	1	E _{off}		0.55		mJ
DIODE CHARACTERISTIC				•		•
Forward voltage	V _{GE} = 0 V, I _F = 30 A V _{GE} = 0 V, I _F = 30 A, T _J = 150°C	V _F		1.2 1.2	1.4	V
Reverse recovery time	$T_J = 25^{\circ}C$ $I_F = 30 \text{ A, } V_R = 200 \text{ V}$ $di_F/dt = 200 \text{ A/}\mu s$	t _{rr}		400		ns
Reverse recovery charge		Q _{rr}		4500		nc
Reverse recovery current		I _{rrm}		23		Α

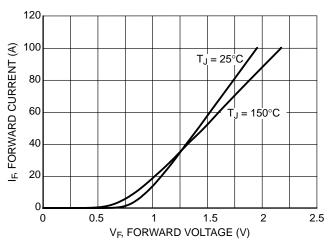
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

20



V_{CE} = 480 V

15

V_{CE} = 480 V

0

0

20

40

60

80

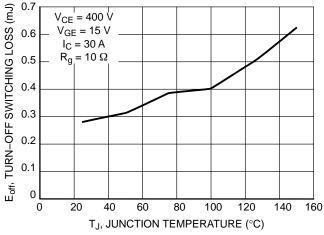
100

120

140

Figure 7. Diode Forward Characteristics

Q_G, GATE CHARGE (nC) Figure 8. Typical Gate Charge



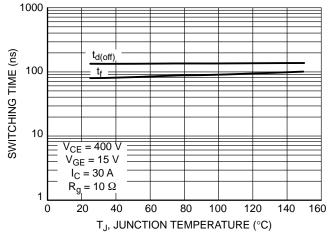
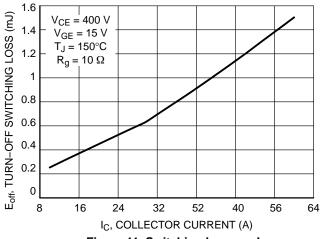


Figure 9. Switching Loss vs. Temperature

Figure 10. Switching Time vs. Temperature



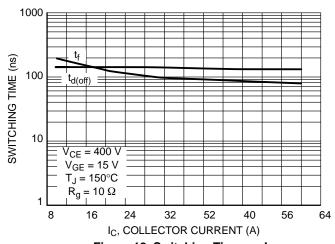


Figure 11. Switching Loss vs. I_C

Figure 12. Switching Time vs. $I_{\rm C}$

TYPICAL CHARACTERISTICS

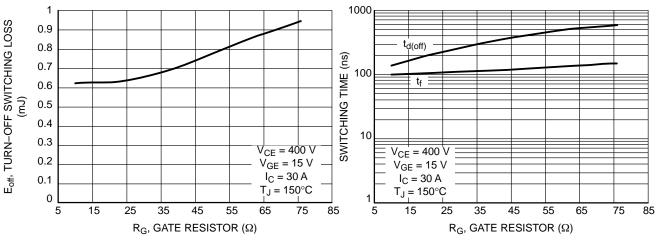


Figure 13. Switching Loss vs. R_G

Figure 14. Switching Time vs. R_G

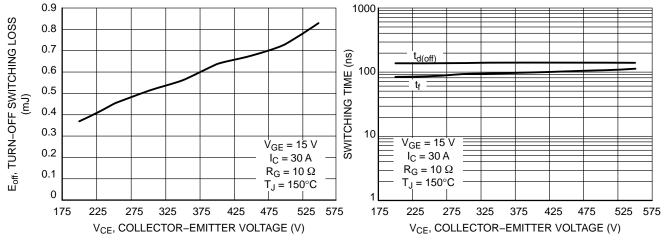


Figure 15. Switching Loss vs. V_{CE}

Figure 16. Switching Time vs. V_{CE}

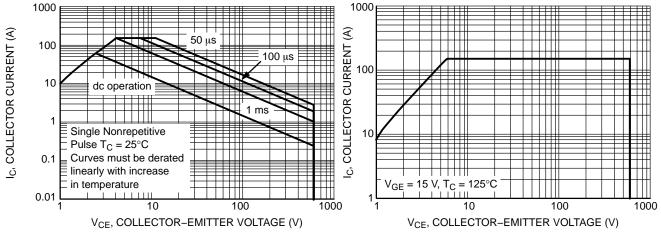


Figure 17. Safe Operating Area

Figure 18. Reverse Bias Safe Operating Area

TYPICAL CHARACTERISTICS

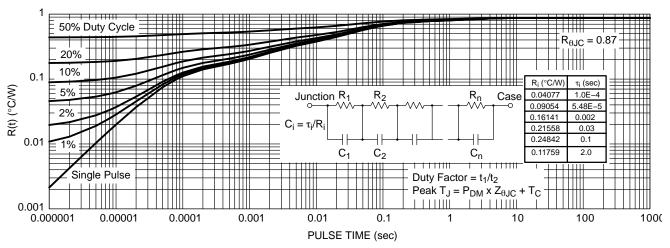


Figure 19. IGBT Transient Thermal Impedance

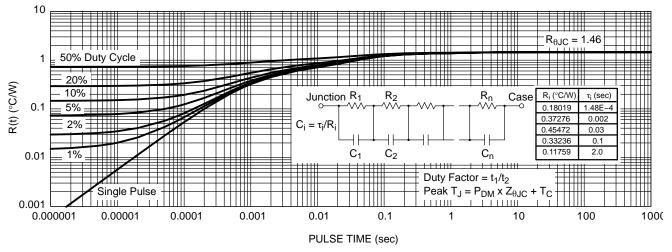


Figure 20. Diode Transient Thermal Impedance

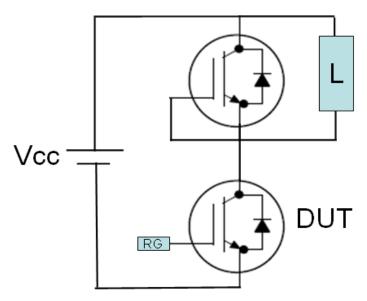


Figure 21. Test Circuit for Switching Characteristics

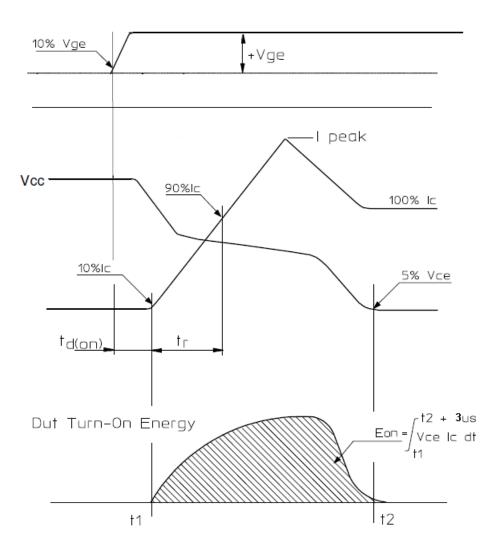


Figure 22. Definition of Turn On Waveform

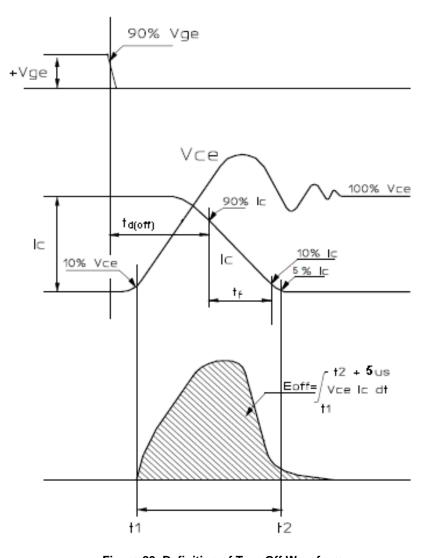
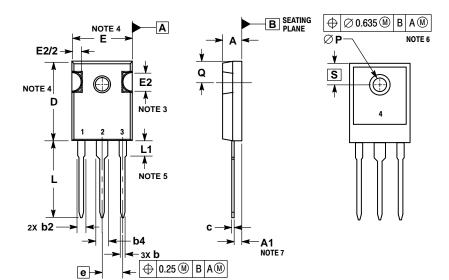


Figure 23. Definition of Turn Off Waveform

PACKAGE DIMENSIONS

TO-247 CASE 340AL **ISSUE B**



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
- SLOT REQUIRED, NOTCH MAY BE ROUNDED. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
 LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY
- \varnothing P SHALL HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91.
 DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.70	5.30	
A1	2.20	2.60	
b	1.00	1.40	
b2	1.65	2.35	
b4	2.60	3.40	
C	0.40	0.80	
D	20.80	21.34	
Ε	15.50	16.25	
E2	4.32	5.49	
е	5.45 BSC		
L	19.80	20.80	
L1	3.81	4.32	
Р	3.55	3.65	
Q	5.40	6.20	
S	6.15 BSC		

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